



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

26-JUN-2003

SUBJECT: ON Semiconductor Final Product/Process Change Notification #12875

TITLE: SOT223 Analog Alternative Capacity in Seremban

EFFECTIVE DATE: 26-Aug-2003

AFFECTED CHANGE CATEGORY: ON Semiconductor Assembly Site

AFFECTED PRODUCT DIVISION: Analog Products Div

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Representative or Joe Duffalo <FFBH9W@onsemi.com>

SAMPLES: Contact Below

Contact your local ON Semiconductor Sales Representative
or Bett Lofts <FFBGFX@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Representative or Bett Lofts <FFBGFX@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the Final Process Change Notification for Initial PCN #12875 notifying customers that ON Semiconductor has completed qualification for additional assembly/test capacity for SOT223 at Seremban, Malaysia. The manufacturing facility in Seremban, Malaysia already assembles and tests other products in the SOT223 package and is TS16949 and ISO9001:2000 certified. The assembly site changes will not affect the case outline, electrical or thermal characteristics of the devices.

Samples are available upon request.

At the expiration of this PCN (60 Days), the devices listed below may be processed at either the Seremban location or the current PSI site.



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RELIABILITY DATA SUMMARY:

Qualification Data :

TEST NAME	TEST CONDITIONS	Accept	Read Point	SS	Lots
High Temp(HTOL) Operating Life	Ta=125DegC for 1008 hrs or Ta=150DegC for 504 hrs	c=0	0,504,1008	84	3
Highly(HAST) Accelerated PC Stress Test	Ta =130DegC,RH = 85% biased	c=0	0,96	84	3
Autoclave(AC-PC)	Ta =121DegC,RH=100%	c=0	0,96	84	3
Temp(TC-PC) Cycling	Ta = -65DegC to +150DegC for 500 cycles	c=0	0,500	84	3

RELIABILITY DATA SUMMARY:

Results of Preconditioned Reliability Tests at 235DegC

		HAST	AC	TC
		Read Point(Hrs)	Read Point(Hrs)	Read Point(Cycles)
LOT	ID	96	96	500
Qual	A	0/84	0/84	0/84
Qual	B	0/84	0/84	0/84
Qual	C	0/84	0/84	0/84
Control		0/84	0/84	0/84

Results of Preconditioned Reliability Tests at 260DegC

		HAST	AC	TC
		Read Point(Hrs)	Read Point(Hrs)	Read Point(Cycles)
LOT	ID	96	96	500
Qual	A	0/84	0/84	0/84
Qual	B	0/84	0/84	0/84
Qual	C	0/84	0/84	0/84
Control		0/84	0/84	0/84

ELECTRICAL CHARACTERISTIC SUMMARY: N/A

CHANGED PART IDENTIFICATION:

Assembly location can be determined from date code information marked on the device.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART

- LM317MBSTT3
- LM317MSTT3
- MC33269ST-3.3T3
- MC33275ST-2.5T3
- MC33275ST-3.0T3
- MC33275ST-3.3T3
- MC33275ST-5.0T3
- MC33375ST-1.8T3



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MC33375ST-2.5T3
MC33375ST-3.0T3
MC33375ST-3.3T3
MC33375ST-5.0T3
MC34268STT3
NCP1117ST12T3
NCP1117ST15T3
NCP1117ST18T3
NCP1117ST20T3
NCP1117ST25T3
NCP1117ST285T3
NCP1117ST33T3
NCP1117ST50T3
NCP1117STAT3